

Title (en)  
Polishing apparatus

Title (de)  
Poliervorrichtung

Title (fr)  
Appareil de polissage

Publication  
**EP 2289668 A2 20110302 (EN)**

Application  
**EP 10251498 A 20100826**

Priority  
JP 2009200690 A 20090831

Abstract (en)  
The polishing apparatus (10) is capable of improving accuracy of polishing a work (W). The work (W) is pressed onto a polishing cloth (11), with an elastic sheet (36), by a pressing force generated by second pressing means (34) and applied to a carrier (28) and inner pressure of a first fluid chamber (38) generated by a fluid supplied thereto, so as to polish the work (W). The fluid, which has been downwardly supplied into the first fluid chamber (38), horizontally flows outward in the first fluid chamber (38), collides with a side wall of a concave part (23) of a board-shaped member (22) and flows upward, and then the fluid is discharged outside from a fluid outlet (44), thereby a fluid feeding member (31) follows movement of the elastic sheet (36) and maintains parallel thereto, and the fluid feeding member (31) is centered in the first fluid chamber (38).

IPC 8 full level  
**B24B 37/30** (2012.01); **H01L 21/304** (2006.01)

CPC (source: EP US)  
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Citation (applicant)  
JP 2000317819 A 20001121 - TOKYO SEIMITSU CO LTD

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